

USB PORT TRANSIENT SUPPRESSORS

FEATURES

- Qualification in Accordance With AEC-Q100⁽¹⁾
- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- Design to Protect Submicron 3-V or 5-V Circuits from Noise Transients
- Port ESD Protection Capability Exceeds:
 15-kV Human Body Model
 - 2-kV Machine Model
- Available in a WCSP Chip-Scale Package
- Stand-Off Voltage ... 6 V Min
- Low Current Leakage . . . 1 μA Max at 6 V
- Low Capacitance . . . 35 pF Typ

 Contact Texas Instruments for details. Q100 qualification data available on request.

APPLICATIONS

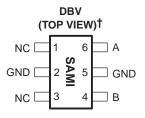
• USB 1.1 Host, Hub, or Peripheral Ports

DESCRIPTION

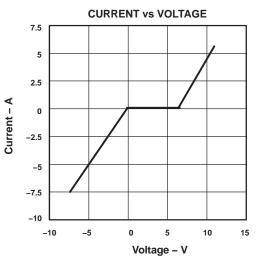
The SN65220 is a single transient voltage suppressor designed to provide electrical noise transient protection to universal serial bus (USB) 1.1 ports. Note that the input capacitance of the device makes it unsuitable for high-speed USB 2.0 applications.

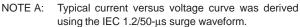
Any cabled I/O can be subjected to electrical noise transients from various sources. These noise transients can cause damage to the USB transceiver and/or the USB ASIC if they are of sufficient magnitude and duration.

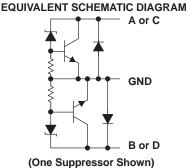
USB ports are typically implemented in 3-V or 5-V digital CMOS with limited ESD protection. The SN65220 can significantly increase the port ESD protection level and reduce the risk of damage to the circuits of the USB port. The IEC1000-4-2 ESD performance of the SN65220 is measured at the system level. Therefore, system design impacts the results of these tests. A high compliance level may be attained with proper board design and layout.



NC – No internal connection When read horizontally, pin 1 is the bottom left pin.







NOTE: All GND terminals should be connected to ground.

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SN65220-Q1



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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

IEC1000-4-2 COMPLIANCE LEVEL

1504000 4 0	MAXIMUM TEST VOLTAGE			
IEC1000-4-2 COMPLIANCE LEVEL	CONTACT DISCHARGE (kV)	AIR DISCHARGE (kV)		
1	2	2		
2	4	4		
3	6	8		
4	8	15		

PACKAGE/ORDERING INFORMATION

PRODUCT	SUPRESSORS	TA	PACKAGE	PACKAGE DESIGNATOR	MARKED AS	ORDER NUMBER
SN65220	1	–40°C to 85°C	SOT23-6	DBV	SAMI	SN65220IDBVRQ1 (Mini Reel)

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted⁽¹⁾

	UNIT
Continuous power dissipation	See Dissipation Rating Table
Electrostatic discharge	15 kV(2), 2 kV(3)
Peak power dissipation, PD(peak)	60 W
Peak forward surge current, IFSM	3 A
Peak reverse surge current, IRSM	–9 A
Storage temperature range, T _{Stg}	−65°C to 150°C

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) Human Body Model - Tested in accordance with JEDEC Standard 22, Test Method A114-A.

(3) Charged Device Model – Tested in accordance with JEDEC Standard 22, Test Method C101.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25^{\circ}C$	DERATING FACTOR	T _A = 70°C	T _A = 85°C
	POWER RATING	ABOVE T _A = 25°C [‡]	POWER RATING	POWER RATING
DBV	385 mW	3.1 mW/°C	246 mW	200 mW

[‡] This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

recommended operating conditions

	MIN	MAX	UNIT
Operating free-air temperature, T _A	-40	85	°C

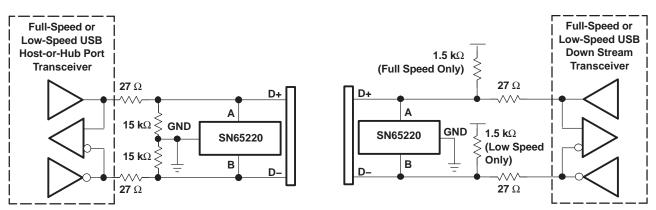


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electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
l _{lkg}	Leakage current	VI = 6 V at A, B, C, or D terminals			1	μΑ
V _(BR)	Breakdown voltage	VI = 1 mA at A, B, C, or D terminals	6.5	7	8	V
CIN	Input capacitance to ground	V _I = 0.4 sin (4E6πt) + 0.5 V		35		pF

APPLICATION INFORMATION



DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- È. Falls within JEDEC MO-178 Variation AB, except minimum lead width.



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